

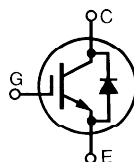
High Voltage, High Gain BIMOSFET™ Monolithic Bipolar MOS Transistor

IXBA10N300HV IXBH10N300HV

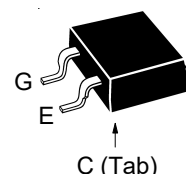
$$V_{CES} = 3000V$$

$$I_{C110} = 10A$$

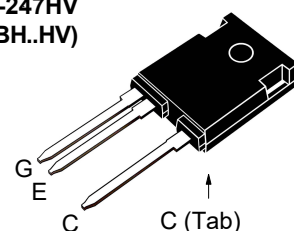
$$V_{CE(sat)} \leq 2.8V$$



TO-263HV
(IXBA..HV)



TO-247HV
(IXBH..HV)



G = Gate C = Collector
E = Emitter Tab = Collector

Symbol	Test Conditions	Maximum Ratings	
V_{CES}	$T_C = 25^\circ C$ to $150^\circ C$	3000	V
V_{CGR}	$T_J = 25^\circ C$ to $150^\circ C$, $R_{GE} = 1M\Omega$	3000	V
V_{GES}	Continuous	± 20	V
V_{GEM}	Transient	± 30	V
I_{C25}	$T_C = 25^\circ C$	34	A
I_{C110}	$T_C = 110^\circ C$	10	A
I_{CM}	$T_C = 25^\circ C$, 1ms	88	A
SSOA (RBSOA)	$V_{GE} = 15V$, $T_{VJ} = 125^\circ C$, $R_G = 10\Omega$ Clamped Inductive Load	$I_{CM} = 80$ 1500	A V
T_{SC} (SCSOA)	$V_{GE} = 15V$, $T_J = 125^\circ C$, $R_G = 82\Omega$, $V_{CE} = 1500V$, Non-Repetitive	10	μs
P_c	$T_C = 25^\circ C$	180	W
T_J		-55 ... +150	$^\circ C$
T_{JM}		150	$^\circ C$
T_{stg}		-55 ... +150	$^\circ C$
T_L	Maximum Lead Temperature for Soldering	300	$^\circ C$
T_{SOLD}	1.6 mm (0.062 in.) from Case for 10s	260	$^\circ C$
F_c	Mounting Force (TO-263HV)	10..65 / 2.2..14.6	N/lb
M_d	Mounting Torque (TO-247HV)	1.13/10	Nm/lb.in
Weight	TO-263HV	2.5	g
	TO-247HV	6.0	g

Features

- High Blocking Voltage
- Anti-Parallel Diode
- Low Conduction Losses

Advantages

- Low Gate Drive Requirement
- High Power Density

Applications

- Switch-Mode and Resonant-Mode Power Supplies
- Uninterruptible Power Supplies (UPS)
- Laser Generators
- Capacitor Discharge Circuits
- AC Switches

Symbol	Test Conditions ($T_J = 25^\circ C$ Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
BV_{CES}	$I_C = 250\mu A$, $V_{GE} = 0V$	3000		V
$V_{GE(th)}$	$I_C = 250\mu A$, $V_{CE} = V_{GE}$	3.0		5.0 V
I_{CES}	$V_{CE} = 0.8 \cdot V_{CES}$, $V_{GE} = 0V$ $T_J = 125^\circ C$			25 μA 500 μA
I_{GES}	$V_{CE} = 0V$, $V_{GE} = \pm 20V$			± 100 nA
$V_{CE(sat)}$	$I_C = 10A$, $V_{GE} = 15V$, Note 1 $T_J = 125^\circ C$		2.2 2.7	2.8 V V

Symbol Test Conditions(T_J = 25°C Unless Otherwise Specified)**Characteristic Values**

		Min.	Typ.	Max.
g_{fs}	I _C = 10A, V _{CE} = 10V, Note 1	6	11	S
C_{ies}	V _{CE} = 25V, V _{GE} = 0V, f = 1MHz		1044	pF
C_{oes}			42	pF
C_{res}			14	pF
Q_g	I _C = 10A, V _{GE} = 15V, V _{CE} = 1000V		46	nC
Q_{ge}			5	nC
Q_{gc}			20	nC
t_{d(on)}	Resistive Switching Times, T_J = 25°C I _C = 10A, V _{GE} = 15V V _{CE} = 960V, R _G = 10Ω		36	ns
t_r			340	ns
t_{d(off)}			100	ns
t_f			1850	ns
t_{d(on)}	Resistive Switching Times, T_J = 125°C I _C = 10A, V _{GE} = 15V V _{CE} = 960V, R _G = 10Ω		40	ns
t_r			765	ns
t_{d(off)}			120	ns
t_f			2010	ns
R_{thJC}	TO-247HV		0.69	°C/W
R_{thCS}				°C/W

Reverse Diode**Symbol Test Conditions**(T_J = 25°C Unless Otherwise Specified)**Characteristic Values**

		Min.	Typ.	Max.
V_F	I _F = 10A, V _{GE} = 0V			2.7 V
t_{rr}	I _F = 5A, V _{GE} = 0V, -di _F /dt = 100A/μs V _R = 100V, V _{GE} = 0V		1.6	μs
I_{RM}			23	A
Q_{RM}			18.6	μC

Note 1: Pulse test, t ≤ 300μs, duty cycle, d ≤ 2%.

Littelfuse reserves the right to change limits, test conditions and dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents:

4,835,592	4,931,844	5,049,961	5,237,481	6,162,665	6,404,065 B1	6,683,344	6,727,585	7,005,734 B2	7,157,338B2
4,860,072	5,017,508	5,063,307	5,381,025	6,259,123 B1	6,534,343	6,710,405 B2	6,759,692	7,063,975 B2	
4,881,106	5,034,796	5,187,117	5,486,715	6,306,728 B1	6,583,505	6,710,463	6,771,478 B2	7,071,537	

Fig. 1. Output Characteristics @ $T_J = 25^\circ\text{C}$

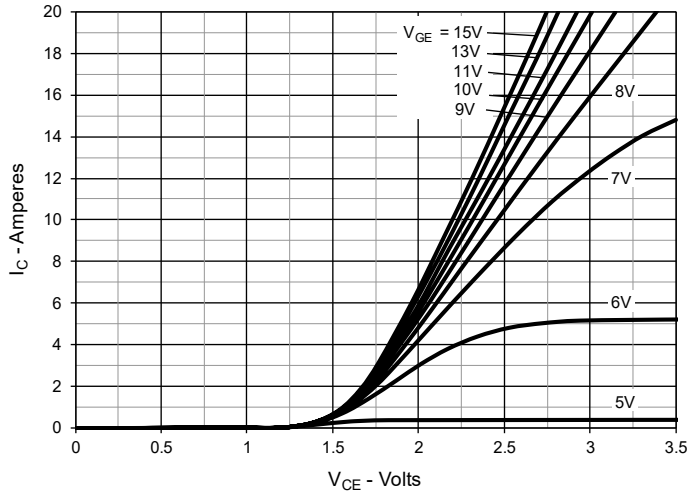


Fig. 2. Extended Output Characteristics @ $T_J = 25^\circ\text{C}$

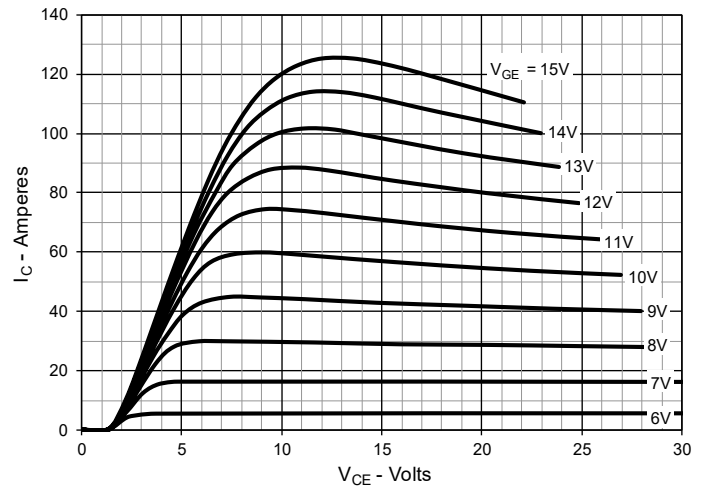


Fig. 3. Output Characteristics @ $T_J = 125^\circ\text{C}$

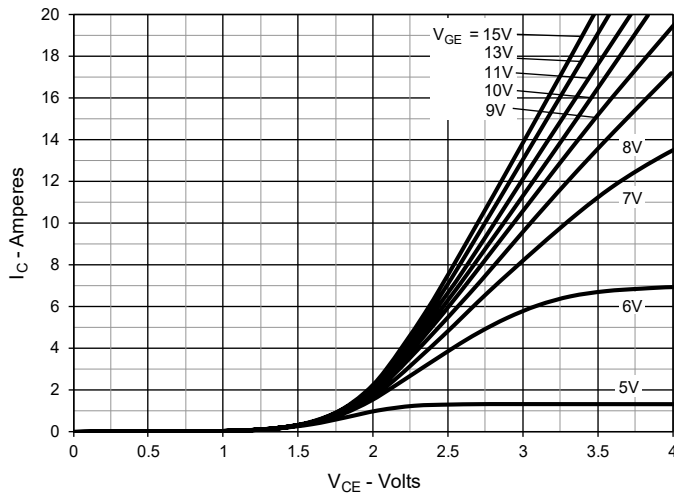


Fig. 4. Dependence of $V_{CE(sat)}$ on Junction Temperature

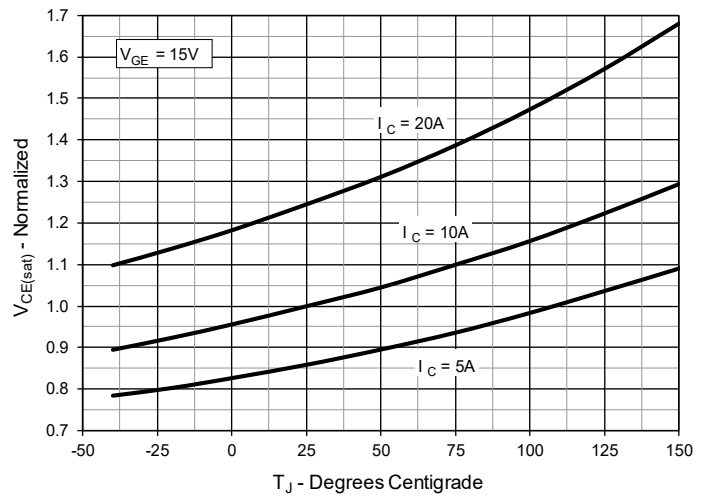


Fig. 5. Collector-to-Emitter Voltage vs. Gate-to-Emitter Voltage

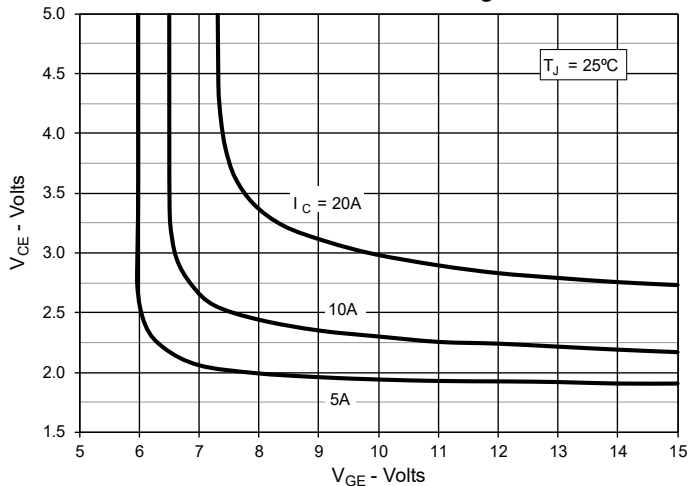


Fig. 6. Input Admittance

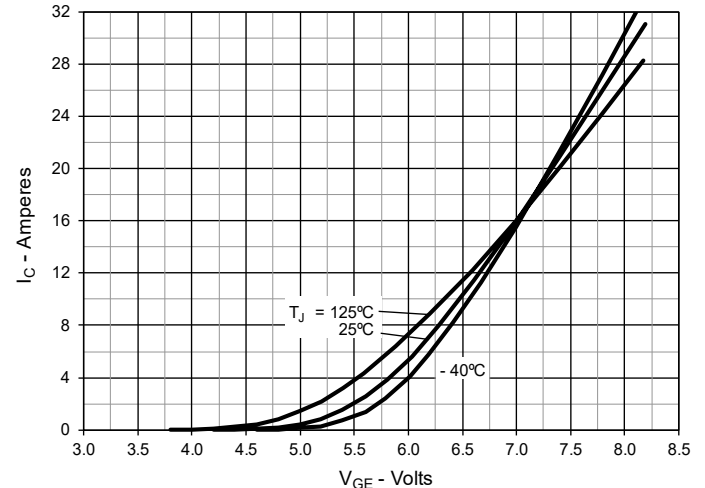


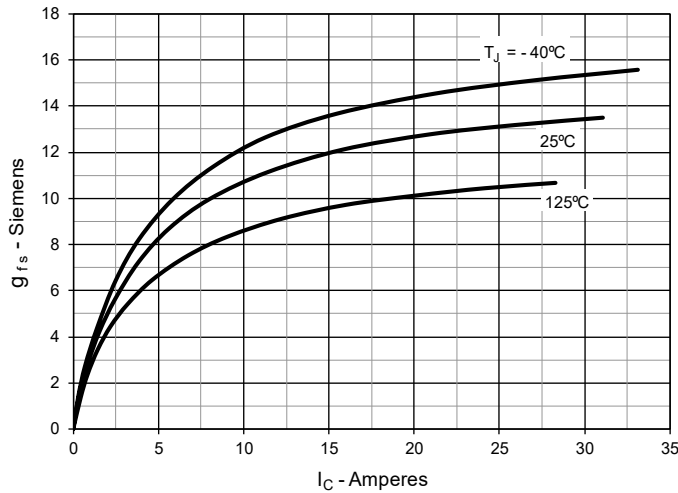
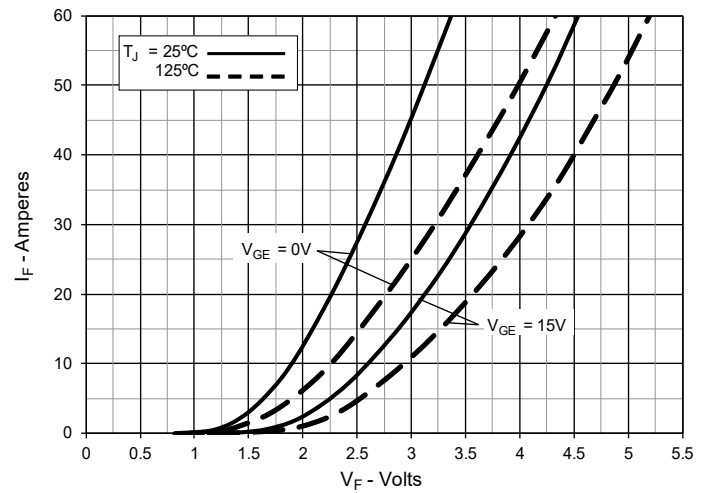
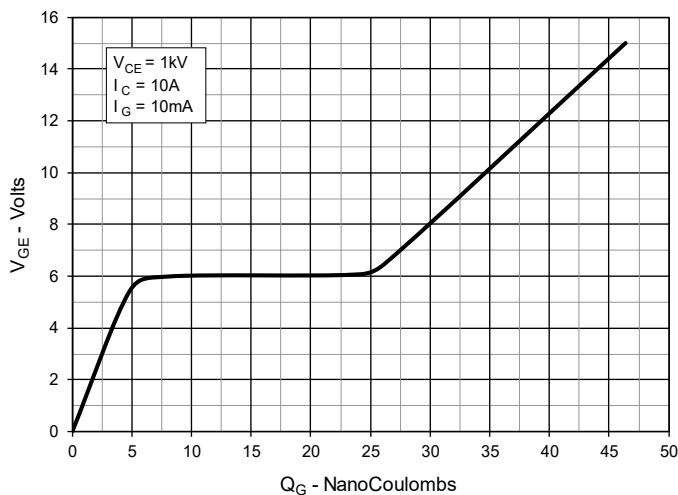
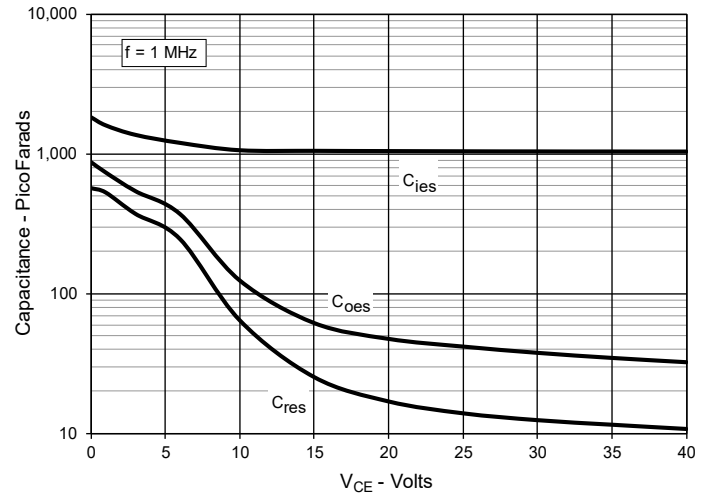
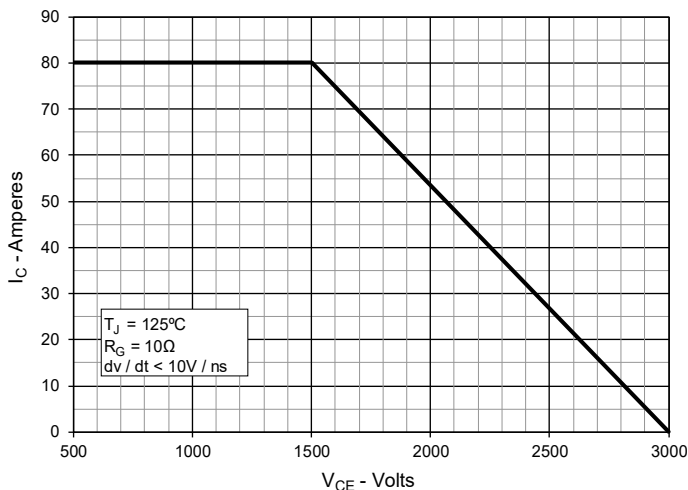
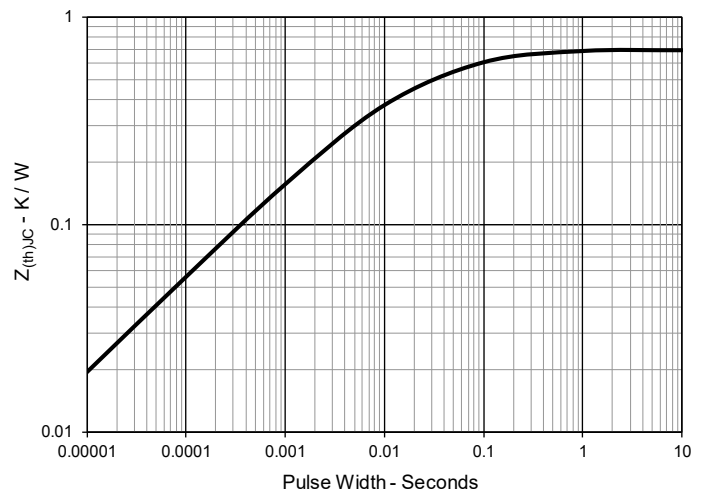
Fig. 7. Transconductance

Fig. 8. Forward Voltage Drop of Intrinsic Diode

Fig. 9. Gate Charge

Fig. 10. Capacitance

Fig. 11. Reverse-Bias Safe Operating Area

Fig. 12. Maximum Transient Thermal Impedance


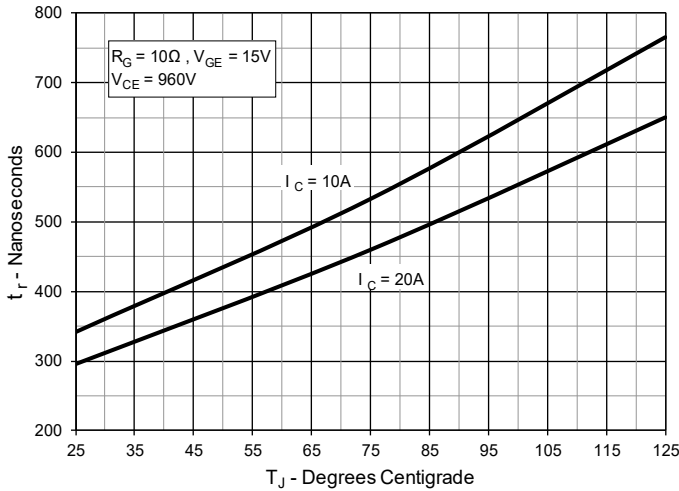
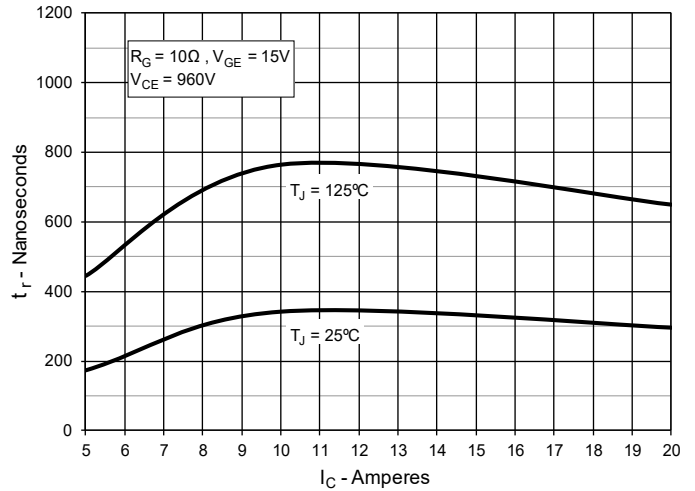
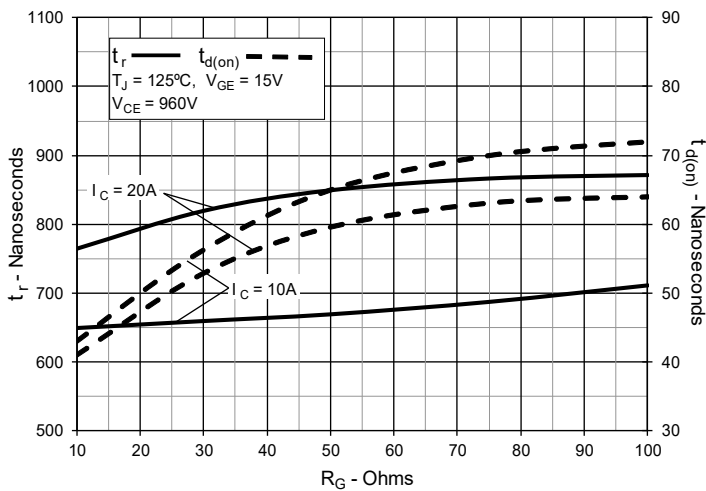
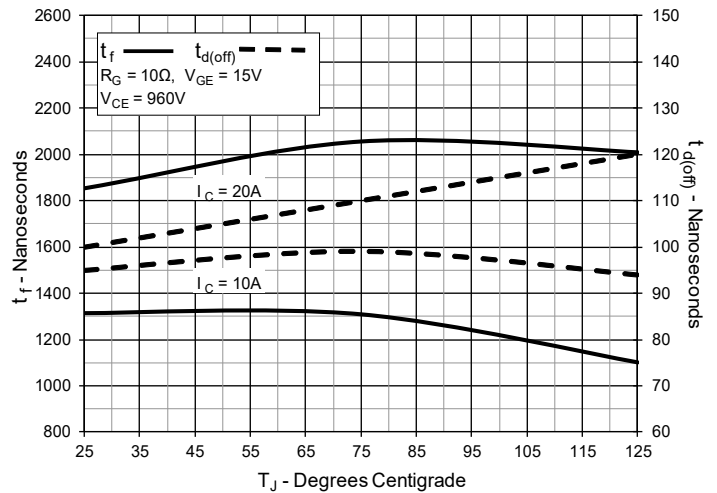
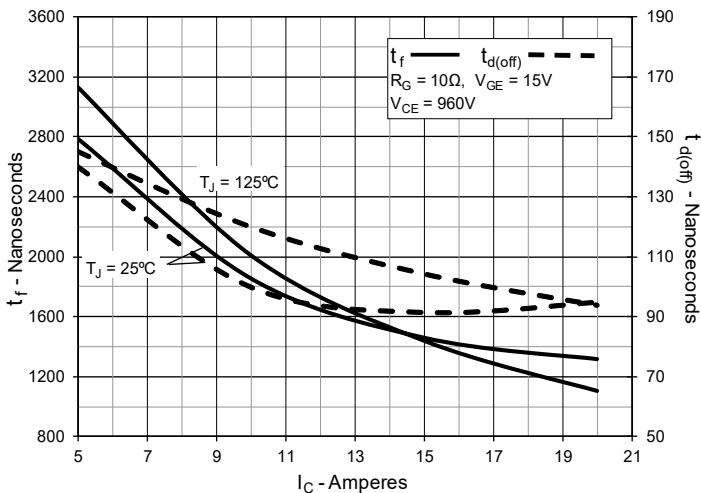
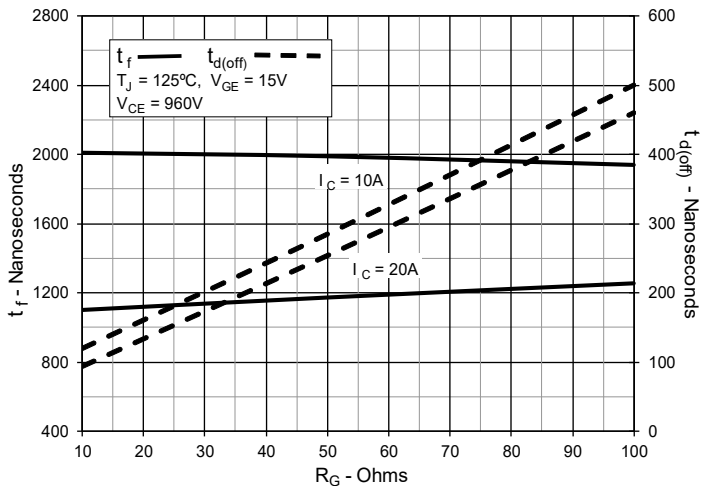
Fig. 13. Resistive Turn-on Rise Time vs. Junction Temperature

Fig. 14. Resistive Turn-on Rise Time vs. Collector Current

Fig. 15. Resistive Turn-on Switching Times vs. Gate Resistance

Fig. 16. Resistive Turn-off Switching Times vs. Junction Temperature

Fig. 17. Resistive Turn-off Switching Times vs. Collector Current

Fig. 28. Resistive Turn-off Switching Times vs. Gate Resistance


Fig. 19. Forward-Bias Safe Operating Area
@ $T_C = 25^\circ\text{C}$

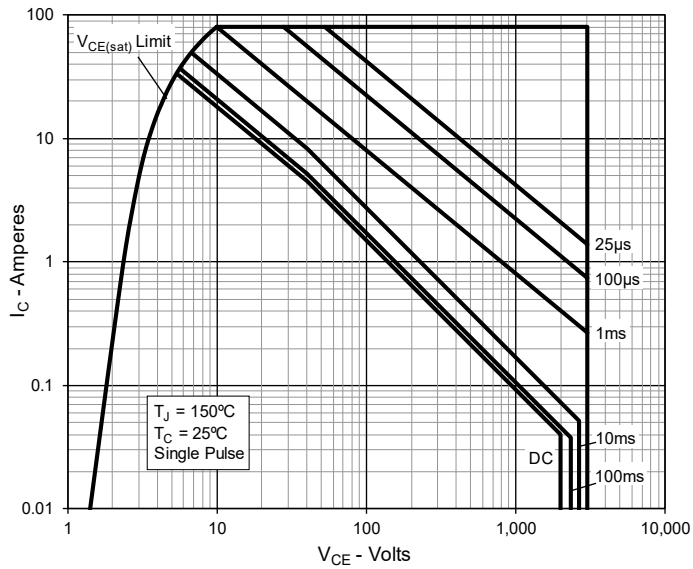
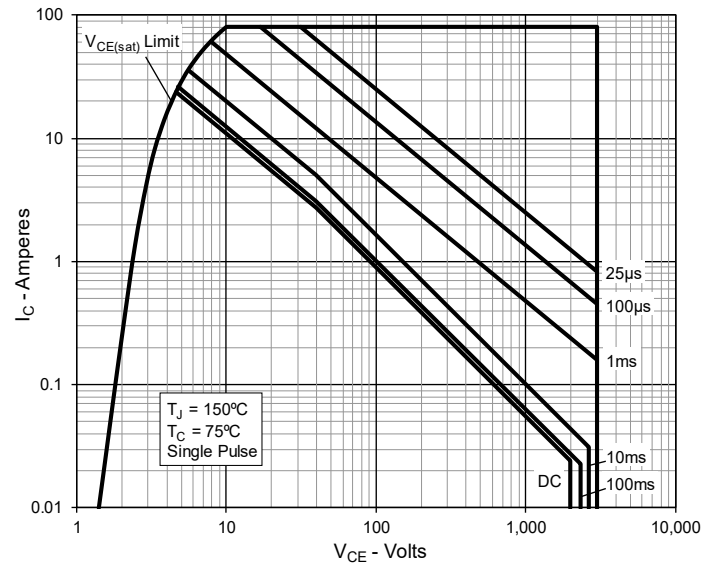
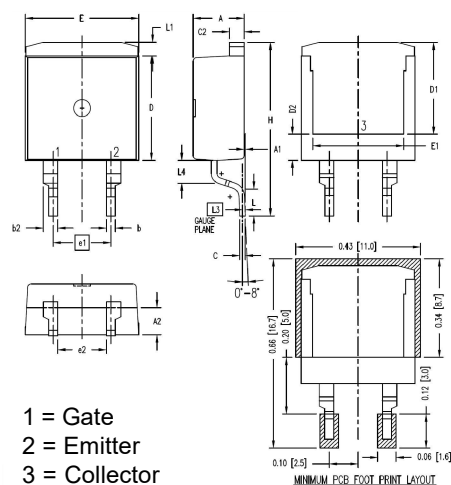
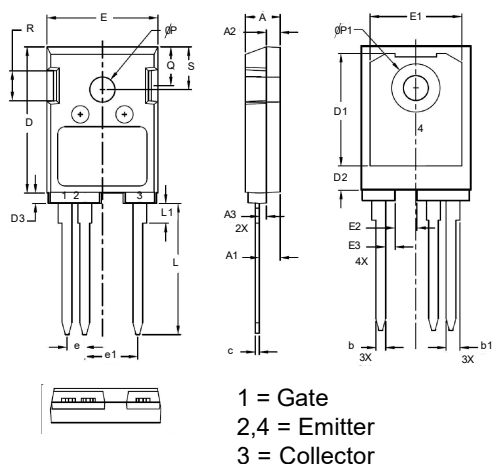


Fig. 20. Forward-Bias Safe Operating Area
@ $T_C = 75^\circ\text{C}$



TO-263HV Outline


SYM	INCHES		MILLIMETER	
	MIN	MAX	MIN	MAX
A	.170	.185	4.30	4.70
A1	.000	.008	0.00	0.20
A2	.091	.098	2.30	2.50
b	.028	.035	0.70	0.90
b2	.046	.054	1.18	1.38
C	.018	.024	0.45	0.60
C2	.049	.055	1.25	1.40
D	.354	.370	9.00	9.40
D1	.311	.327	7.90	8.30
D2	.083	.098	2.10	2.50
E	.386	.402	9.80	10.20
E1	.307	.323	7.80	8.20
e1	.200	BSC	5.08	BSC
(e2)	.163	.174	4.13	4.43
H	.591	.614	15.00	15.60
L	.079	.102	2.00	2.60
L1	.039	.055	1.00	1.40
L3	.010	BSC	0.254	BSC
(L4)	.071	.087	1.80	2.20

TO-247HV Outline


SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.193	.201	4.90	5.10
A1	.114	.122	2.90	3.10
A2	.075	.083	1.90	2.10
A3	.035	.043	0.90	1.10
b	.053	.059	1.35	1.50
b1	.075	.083	1.90	2.10
c	.022	.030	0.55	0.75
D	.819	.843	20.80	21.40
D1	.638	.646	16.20	16.40
D2	.134	.146	3.40	3.70
D3	.055	.063	1.40	1.60
E	.622	.638	15.80	16.20
E1	.520	.528	13.20	13.40
E2	.118	.126	3.00	3.20
E3	.051	.059	1.30	1.50
e	.100	BSC	2.54	BSC
e1	.300	BSC	7.62	BSC
L	.724	.748	18.40	19.00
L1	.106	.118	2.70	3.00
øP	.138	.142	3.50	3.60
øP1	.272	.280	6.90	7.10
Q	.216	.224	5.50	5.70
R	.165	.169	4.20	4.30
S	.240	.248	6.10	6.30

